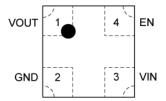
Ordering Information

| Part Number | Marking | Soft-Start | Load Discharge | Package |
|-------------|---------|------------|----------------|--------------------------------------|
| MIC94044YFL | P5 | 1ms | | 4-Pin 1.2mm x 1.2mm MLF [®] |
| MIC94045YFL | P6 | 1ms | 1 | 4-Pin 1.2mm x 1.2mm MLF [®] |

Notes:

- 1. MLF[®] Pin 1 Identifier symbol is "●".
- 2. Over bar symbol () may not be to scale.
- $3. \quad \mathsf{MLF}^{\$} \ \mathsf{is} \ \mathsf{a} \ \mathsf{GREEN} \ \mathsf{RoHS}\text{-}\mathsf{compliant} \ \mathsf{package}. \ \mathsf{Lead} \ \mathsf{finish} \ \mathsf{is} \ \mathsf{NiPdAu}. \ \mathsf{Mold} \ \mathsf{compound} \ \mathsf{is} \ \mathsf{Halogen} \ \mathsf{Free}.$

Pin Configuration



4-Pin 1.2mm x 1.2mm MLF^{\otimes} (Top View)

Pin Description

| Pin Number | Pin Name | Description |
|------------|-----------------|---|
| 1 | V_{OUT} | Drain of P-channel MOSFET. |
| 2 | GND | Ground should be connected to electrical ground. |
| 3 | V _{IN} | Source of P-channel MOSFET. |
| 4 | EN | Enable (Input): Active-high CMOS/TTL control input for switch. Do not leave floating. |

Absolute Maximum Ratings (1)

| Input Voltage (V _{IN}) | +6V |
|--|----------------|
| Enable Voltage (V _{EN}) | |
| Continuous Drain Current (I _D) (3) | |
| T _A = 25°C | ±3A |
| T _A = 85°C | ±2A |
| Pulsed Drain Current (I _{DP}) ⁽⁴⁾ | |
| Continuous Diode Current (I _S) ⁽⁵⁾ | –50mA |
| Storage Temperature (T _s) | 55°C to +150°C |
| Storage Temperature (T _s) ESD Rating – HBM ⁽⁶⁾ | 3k\ |

Operating Ratings (2)

| Input Voltage (V _{IN}) | +1.7 to +5.5V |
|---|-----------------|
| Junction Temperature (T _J) | –40°C to +125°C |
| Package Thermal Resistance | |
| 1.2mm x 1.2mm MLF [®] -4L(θ_{JC}) |)90°C/W |

Electrical Characteristics (7)

 T_A = 25°C, bold values indicate –40°C< T_J < +85°C, unless noted.

| Symbol | Parameter | Condition | Min | Тур | Max | Units |
|--------------------------|---|--|-----|------|-----|-------|
| V _{EN_TH} | Enable Threshold Voltage | $V_{IN} = 1.7V \text{ to } 4.5V, I_D = -250 \mu\text{A}$ | 0.4 | | 1.2 | V |
| ΙQ | Quiescent Current | $V_{IN} = V_{EN} = 5.5V$, $I_D = OPEN$ Measured on V_{IN} | | 2.25 | 10 | μA |
| I _{EN} | Enable Input Current | V _{IN} = V _{EN} = 5.5V, I _D = OPEN | | 0.1 | 1 | μΑ |
| I _{SHUT-Q} | Quiescent Current (shutdown) | V_{IN} = +5.5V, V_{EN} = 0V, I_D = OPEN Measured on V_{IN} | | 0.1 | 1 | μA |
| I _{SHUT-SWITCH} | OFF State Leakage Current | V_{IN} = +5.5V, V_{EN} = 0V, I_{D} = SHORT Measured on V_{OUT} , $^{(7)}$ | | 0.1 | 1 | μA |
| R _{DS(ON)} | P-Channel Drain to Source ON Resistance | V _{IN} = +5.0V, I _D = -100mA, V _{EN} = 1.5V | | 28 | 55 | mΩ |
| | | V _{IN} = +4.5V, I _D = -100mA, V _{EN} = 1.5V | | 30 | 60 | mΩ |
| | | V_{IN} = +3.6V, I_D = -100mA, V_{EN} = 1.5V | | 33 | 65 | mΩ |
| | | V _{IN} = +2.5V, I _D = -100mA, V _{EN} = 1.5V | | 45 | 90 | mΩ |
| | | V _{IN} = +1.8V, I _D = -100mA, V _{EN} = 1.5V | | 72 | 145 | mΩ |
| | | V _{IN} = +1.7V, I _D = -100mA, V _{EN} = 1.5V | | 82 | 160 | mΩ |
| R _{SHUTDOWN} | Turn-Off Resistance | V _{IN} = +3.6V, I _{TEST} = 1mA, V _{EN} = 0V MIC94045 | | 200 | 400 | Ω |

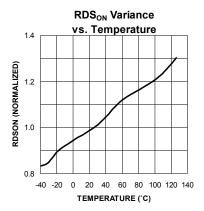
Dynamic

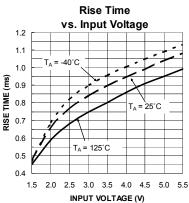
| ton_dly | Turn-On Delay Time | $V_{IN} = +3.6V, I_D = -100mA, V_{EN} = 1.5V$ | 0.2 | 0.85 | 1.5 | ms |
|-----------------------|---------------------|--|-----|------|-----|----|
| ton_rise | Turn-On Rise Time | V _{IN} = +3.6V, I _D = -100mA, V _{EN} = 1.5V | 0.4 | 1 | 1.5 | ms |
| toff_DLY | Turn-Off Delay Time | $V_{IN} = +3.6V$, $I_D = -100$ mA, $V_{EN} = 0$ V | | 100 | 200 | ns |
| t _{OFF_FALL} | Turn-Off Fall Time | $V_{IN} = +3.6V$, $I_D = -100$ mA, $V_{EN} = 0$ V | | 20 | 100 | ns |
| | | (No Output Capacitor) | | | | |

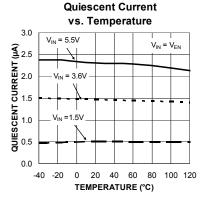
Notes:

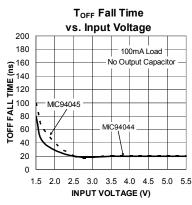
- 1. Exceeding the absolute maximum rating may damage the device.
- 2. The device is not guaranteed to function outside its operating rating.
- 3. With thermal contact to PCB. See power dissipation considerations section.
- 4. Pulse width <300µs with < 2% duty cycle.
- 5. Continuous body diode current conduction (reverse conduction, i.e. V_{OUT} to V_{IN}) is not recommended.
- 6. Devices are ESD sensitive. Handling precautions recommended. HBM (Human body model), 1.5kΩ in series with 100pF.
- 7. Measured on the MIC94044YFL.

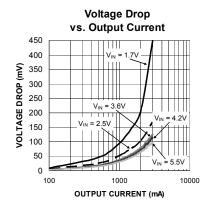
Typical Characteristics

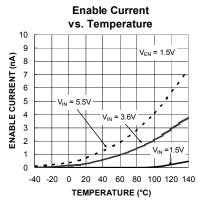


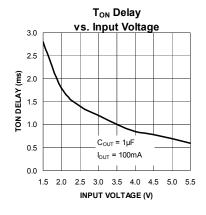


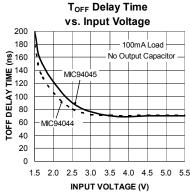


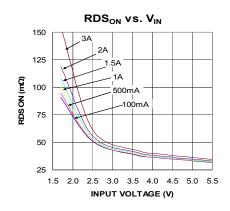


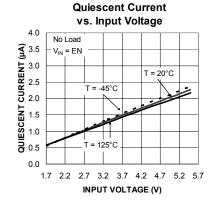


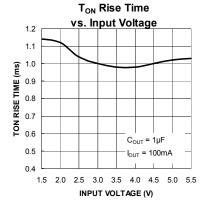


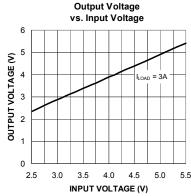




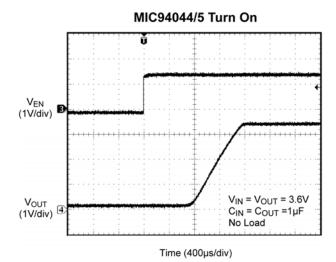


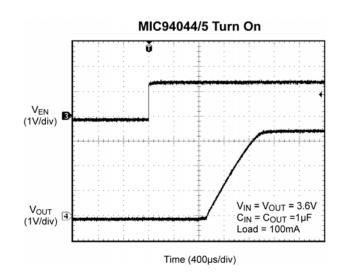


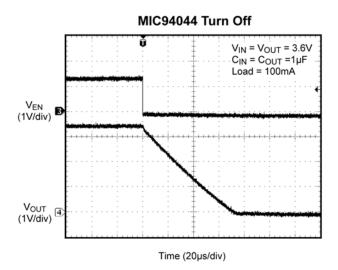


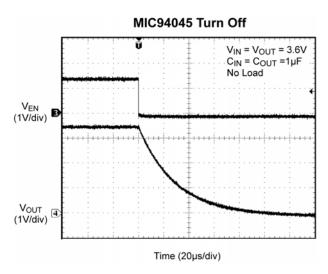


Functional Characteristics









Application Information

Power Switch SOA

The safe operating area (SOA) curve represents the boundary of maximum safe operating current and maximum safe operating ambient temperature.

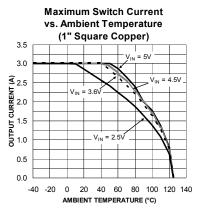


Figure 1: SOA Graph

The curves above show the SOA for various values of V_{IN} , mounted on a typical 1 layer, 1 square inch copper board.

Power Dissipation Considerations

As with all power switches, the current rating of the switch is limited mostly by the thermal properties of the package and the PCB it is mounted on. There is a simple ohms law type relationship between thermal resistance, power dissipation and temperature, which are analogous to an electrical circuit:

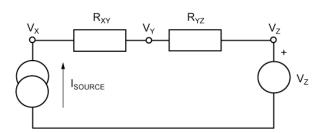


Figure 2: Simple Electrical Circuit

From this simple circuit we can calculate V_X if we know I_{SOURCE} , V_Z and the resistor values, R_{XY} and R_{YZ} using the equation:

$$V_X = I_{SOURCE} (R_{XY} + R_{YZ}) + V_Z$$

Thermal circuits can be considered using these same rules and can be drawn similarly by replacing current sources with power dissipation (in Watts), resistance with thermal resistance (in °C/W) and voltage sources with temperature (in °C).

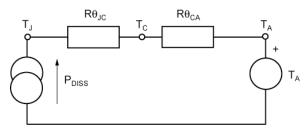


Figure 3: Simple Thermal Circuit

Now replacing the variables in the equation for V_X , we can find the junction temperature (T_J) from power dissipation, ambient temperature and the known thermal resistance of the PCB $(R\theta_{CA})$ and the package $(R\theta_{JC})$.

$$T_J = P_{DISS} x (R\theta_{JC} + R\theta_{CA}) + T_A$$

 P_{DISS} is calculated as I_{SWITCH}^2 x R_{SWmax} . $R\theta_{\text{JC}}$ is found in the operating ratings section of the datasheet and $R\theta_{\text{CA}}$ (the PCB thermal resistance) values for various PCB copper areas is discussed in the document "Designing with Low Dropout Voltage Regulators" available from the Micrel website (LDO Application Hints).

Example:

A switch is intended to drive a 2A load and is placed on a printed circuit board which has a ground plane area of at least 25mm x 25mm (625mm^2). The Voltage source is a Li-ion battery with a lower operating threshold of 3V and the ambient temperature of the assembly can be up to 50°C .

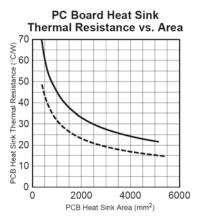


Figure 4: Excerpt from the LDO Book

Summary of variables:

$$I_{SW}$$
 = 2A
 V_{IN} = 3V to 4.2V
 T_A = 50°C
 $R\theta_{JC}$ = 90°C/W from Datasheet
 $R\theta_{CA}$ = 53°C/W Read from Graph in Figure 4
 P_{DISS} = I_{SW}^2 x R_{SWmax}

The worst case switch resistance (R_{SWmax}) at the lowest V_{IN} of 3V is not available in the datasheet, so the next lower value of V_{IN} is used.

$$R_{SWmax}$$
 @ 2.5V = 90m Ω

If this were a figure for worst case R_{SWmax} for 25°C , an additional consideration is to allow for the maximum junction temperature of 125°C , the actual worst case resistance in this case can be 30% higher (See R_{DSON} variance vs. temperature graph). However, $90\text{m}\Omega$ is the maximum over temperature.

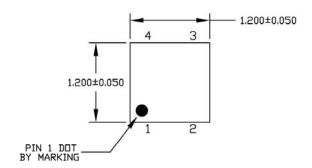
Therefore:

$$T_J = 2^2 \times 0.090 \times (90+53) + 50$$

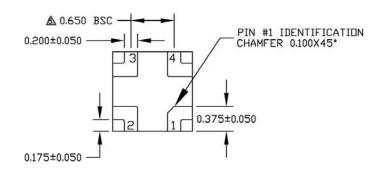
 $T_J = 101^{\circ}C$

This is below the maximum 125°C.

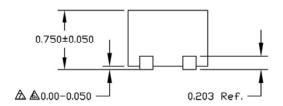
Package Information



TOP VIEW



BOTTOM VIEW



NOTE:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. MAX. PACKAGE WARPAGE IS 0.05 mm.
3. MAXIMUM ALLOWABE BURRS IS 0.076 mm IN ALL DIRECTIONS.
4. PIN #1 ID ON TOP WILL BE LASER/INK MARKED.
5. DIMENSION APPLIES TO METALIZED TERMINAL AND IS MEASURED BETWEEN 0.20 AND 0.25 mm FROM TERMINAL TIP.
5. APPLIED ONLY FOR TERMINALS.

APPLIED FOR EXPOSED PAD AND TERMINALS.

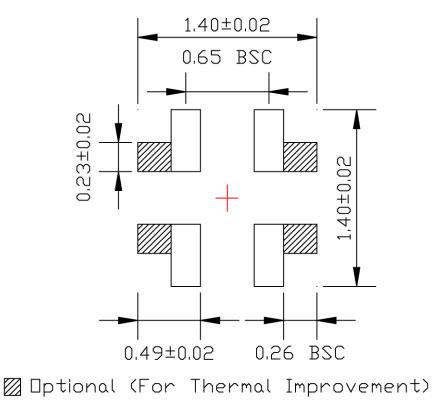
SIDE VIEW

4-Pin 1.2mm x 1.2mm MLF®

Recommended Land Pattern

LP # MLF1212D-4LD-LP-9

All units are in mm
Tolerance ± 0.05 if not noted



Disclaimer: This is only a recommendation based on information available to Micrel from its suppliers. Actual land pattern may have to be significantly different due to various materials and processes used in PCB assembly. Micrel makes no representation or warranty of performance based on the recommended land pattern."

4-Pin 1.2mm x 1.2mm MLF® Land Pattern

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